

CHEMTRONICS®

Technical Data Sheet

TDS # SW

Soder-Wick® Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® is the state of the art in desoldering. Soder-Wick® is especially designed for today's heat sensitive electronic components. Their lighter mass, pure copper braid construction allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds as much as 50% faster than conventional desoldering braids. This design minimizes overheating and requires less "contact" pressure for greater operator control. A full range of sizes and flux types are available, including an unfluxed version and a patented No Clean type. Whatever the requirement, Soder-Wick® has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized weave design for faster wicking and heat transfer
- Halide free
- Minimal risk of heat damage to components and circuit boards

TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- Surface Mount Device Pads
- BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Soder-Wick® Desoldering Braid	
Flux Types:	Rosin Grade WW, Type "R" Patented No Clean Flux
Clean-up Required:	No
Military Specifications:	MIL-F-14256F

Size #	Width Inches	Color	Width Metric
1	.030"	White	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm
5	.145"	Brown	3.7mm
6	.210"	Red	5.3mm
BGA	-	Purple	-

STATIC DISSIPATIVE PACKAGING

Static Dissipative packaging is available on all 5 and 10 foot bobbins. The static dissipative bobbins qualify as electrostatic discharge protective per DOD Standard 1686 and DOD Handbook 263. Meets the static delay rate provision of MIL-B-81705C.

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick[®] desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly smaller than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.

SODER-WICK[®] IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R
NASA NHB5300.4(3A)
NASA SP-5002
NASA NPC200-4
IPC SF-818
BELLCORE TR-NWT-00078

SODER-WICK[®] SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A
MIL-B-81705C
DOD HANDBOOK 263
DOD STANDARD 1686

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics[®] provides a technical hotline to answer your technical and application related questions. The toll free number is:
1-800-TECH-401.

AVAILABILITY

Series:

- 50** Rosin Flux
80 Rosin Flux, SD Bobbin
60 No Clean Flux, SD Bobbin
70 Unfluxed
75 Unfluxed, SD Bobbin

<i>VacuPak[™] Packaging</i>	Part #	Size
The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.	SW18015	1
	SW18025	2
	SW18035	3
	SW18045	4
	SW18055	5

HELPFUL HINTS:

Water Soluble Users: Use the unfluxed **70** or **75** Series to dip in the water soluble flux type you are using and then desolder normally.

Ball Grid Array: Use the Soder-Wick[®] BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

NOTE: This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS[®] does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

MANUFACTURED BY:

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